

N32G455xB/xC/xE/xG

Product Brief

N32G455 series uses a 32-bit ARM Cortex-M4F core with a maximum operating frequency of 144MHz, supporting floating point unit and DSP instructions, integrating up to 512KB Flash, 144KB SRAM, and built-in four 12bit 4.7Msps ADC, four independent rail-to-rail operational amplifiers, seven high-speed comparators, two 1Msps 12bit DAC, integrated multi-channel U(S)ART, I2C, SPI, QSPI, USB, CAN, SDIO communication interface, Built-in cryptographic algorithm hardware acceleration engine

Main features

● CPU core

- 32-bit ARM Cortex-M4 core + FPU, single-cycle hardware multiply instructions, support DSP instructions and MPU
- Built-in 8KB instruction Cache, support Flash acceleration unit execution program 0 wait
- Run up to 144MHz, 180DMIPS

● Memory

- Up to 512KByte embedded Flash memory, support encrypted storage, partition management and data protection, support hardware ECC verification, 100,000 erasing times, 10 years data retention
- Up to 512Kbyte D-Flash (N32G455RGL7 and N32G455VGL7 only), 100,000 erase/write cycles and 20 years data retention
- 144KByte embedded SRAM (including 16KByte Retention RAM), supporting hardware parity check

● High-performance analog interface

- 4x 12bit 5Msps high-speed ADCs, available in 12/10/8/6 bit mode, sampling rate up to 9Msps in 6bit mode and up to 38 external single-ended input channels, supporting differential mode
- 4x rail-to-rail operational amplifiers with built-in programmable gain amplification up to 32 times
- Up to 7x high-speed analog comparators with built-in 64 level adjustable comparison datum
- 2x 12bit DAC, sampling rate 1Msps
- Support external input independent reference voltage source
- All analog interfaces support full voltage from 1.8 to 3.6V

● Clock

- 4MHz~32MHz external high-speed crystal
- 32.768KHz external low-speed crystal
- Internal high-speed RC 8MHz
- Internal low-speed RC 40KHz
- Built-in high-speed PLL
- Supports one-way clock output, which can be configured with system clock, HSE, HSI, or PLL frequency division output

● Reset

- Supports power on, power down, brown-out and external pin reset

- Support watchdog reset, software reset
- **Up to 80 GPIOs with multiplexing function. The maximum flip speed is 50MHz. Most GPIO supports 5V voltage resistance.**
- **Communication interface**
 - 7x U(S)ART interfaces with speeds up to 4.5Mbps, including 3x USART interfaces (supporting ISO7816, IrDA, LIN) and 4x UART interfaces
 - 3x SPI interfaces with speeds up to 36MHz, two of which support I2S
 - 1x QSPI interface with speeds up to 144Mbps
 - 4x I2C interfaces with speeds up to 1MHz, which can be configured in master/slave mode and support dual address response in slave mode
 - 1x USB2.0 Full Speed Device port
 - 2x CAN 2.0B bus interfaces
 - 1x SDIO interface, supporting SD/MMC format
- **2x high-speed DMA controllers, each controller supports 8 channels, channel source address and destination address can be arbitrarily configurable**
- **RTC real-time clock, support leap year perpetual calendar, alarm clock event, periodic wake up, support internal and external clock calibration**
- **Timing counter**
 - 2x 16bit advanced timer counters, support input capture, complementary output, orthogonal coding input and other functions, the highest control accuracy of 6.9ns; Each timer has four independent channels, three of which support 6 complementary PWM output
 - 4x 16bit general timer counters, each timer has four independent channels, support input capture/output comparison /PWM output
 - 2x 16bit basic timer counters
 - 1x 24bit SysTick
 - 1x 7bit Window Watchdog (WWDG)
 - 1x 12bit Independent Watchdog (IWDG)
- **Programming mode**
 - Support SWD/JTAG online debugging interface
 - Support UART and USB Bootloader
- **Security features**
 - Built-in cryptographic algorithm hardware acceleration engine
 - Supports AES, DES, SHA, SM1, SM3, SM4, SM7, and MD5 algorithms
 - Flash Storage encryption, Multi-user Partition Management (MMU)
 - TRNG true random number generator
 - CRC16/32 operation
 - Support write protection (WRP), multiple read protection (RDP) levels (L0/L1/L2)

- Support security startup, program encryption download, security updates
- Support clock failure detection, anti-disassembly detection
- **96-bit UID and 128-bit UCID**
- **Working conditions**
 - Operating voltage range: 1.8V~3.6V
 - Operating temperature range: -40°C ~ 105°C
 - ESD: ±4KV (HBM model), ±1KV (CDM model)
- **Package**
 - QFN36(6mm x 6mm)
 - QFN48 (6mm x 6mm)
 - LQFP48(7mm x 7mm)
 - QFN64(8mm x 8mm)
 - LQFP64(10mm x 10mm)
 - LQFP80(12mm x 12mm)
 - LQFP100(14mm x 14mm)

1 Ordering information

Figure 1-1 N32G455 Series Part Number Information

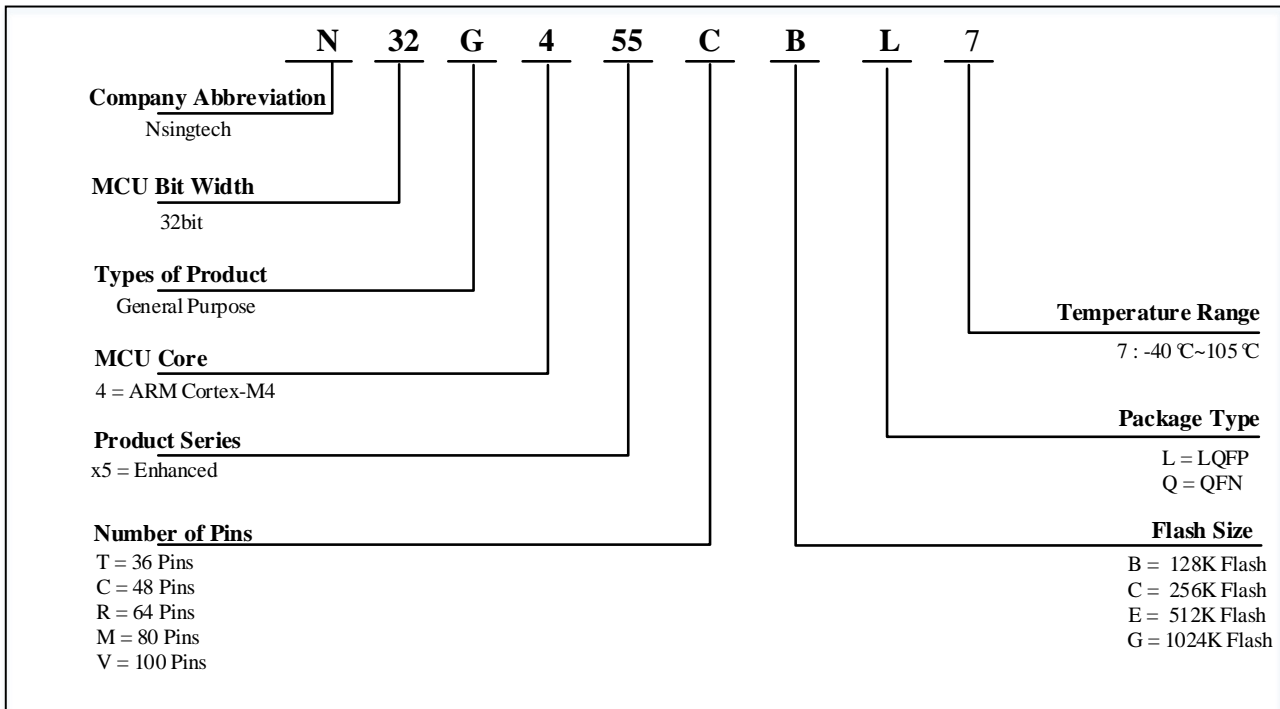


Table 1-1 N32G455 Series Ordering Code

Ordering code ⁽¹⁾	Package	Package size	Packaging ⁽²⁾	SPQ ⁽³⁾	Temperature range
N32G455CBL7	LQFP48	7mm*7mm	Tray	250	-40°C ~ 105°C
N32G455CCL7	LQFP48	7mm*7mm	Tray	250	-40°C ~ 105°C
N32G455CEL7	LQFP48	7mm*7mm	Tray	250	-40°C ~ 105°C
N32G455CEQ7	QFN48	6mm*6mm	Tray	490	-40°C ~ 105°C
N32G455RBL7	LQFP64	10mm*10mm	Tray	160	-40°C ~ 105°C
N32G455RCL7	LQFP64	10mm*10mm	Tray	160	-40°C ~ 105°C
N32G455REL7	LQFP64	10mm*10mm	Tray	160	-40°C ~ 105°C
N32G455RGL7	LQFP64	10mm*10mm	Tray	160	-40°C ~ 105°C
N32G455MBL7	LQFP80	12mm*12mm	Tray	119	-40°C ~ 105°C
N32G455MCL7	LQFP80	12mm*12mm	Tray	119	-40°C ~ 105°C
N32G455MEL7	LQFP80	12mm*12mm	Tray	119	-40°C ~ 105°C
N32G455VBL7	LQFP100	14mm*14mm	Tray	90	-40°C ~ 105°C
N32G455VCL7	LQFP100	14mm*14mm	Tray	90	-40°C ~ 105°C
N32G455VEL7	LQFP100	14mm*14mm	Tray	90	-40°C ~ 105°C
N32G455VGL7	LQFP100	14mm*14mm	Tray	90	-40°C ~ 105°C

1. For the latest detailed ordering information, please refer to the Selection Guide.
2. The packaging provided is the basic packaging. If user has any other requirements, please contact Nsing
3. Minimum packaging quantity.

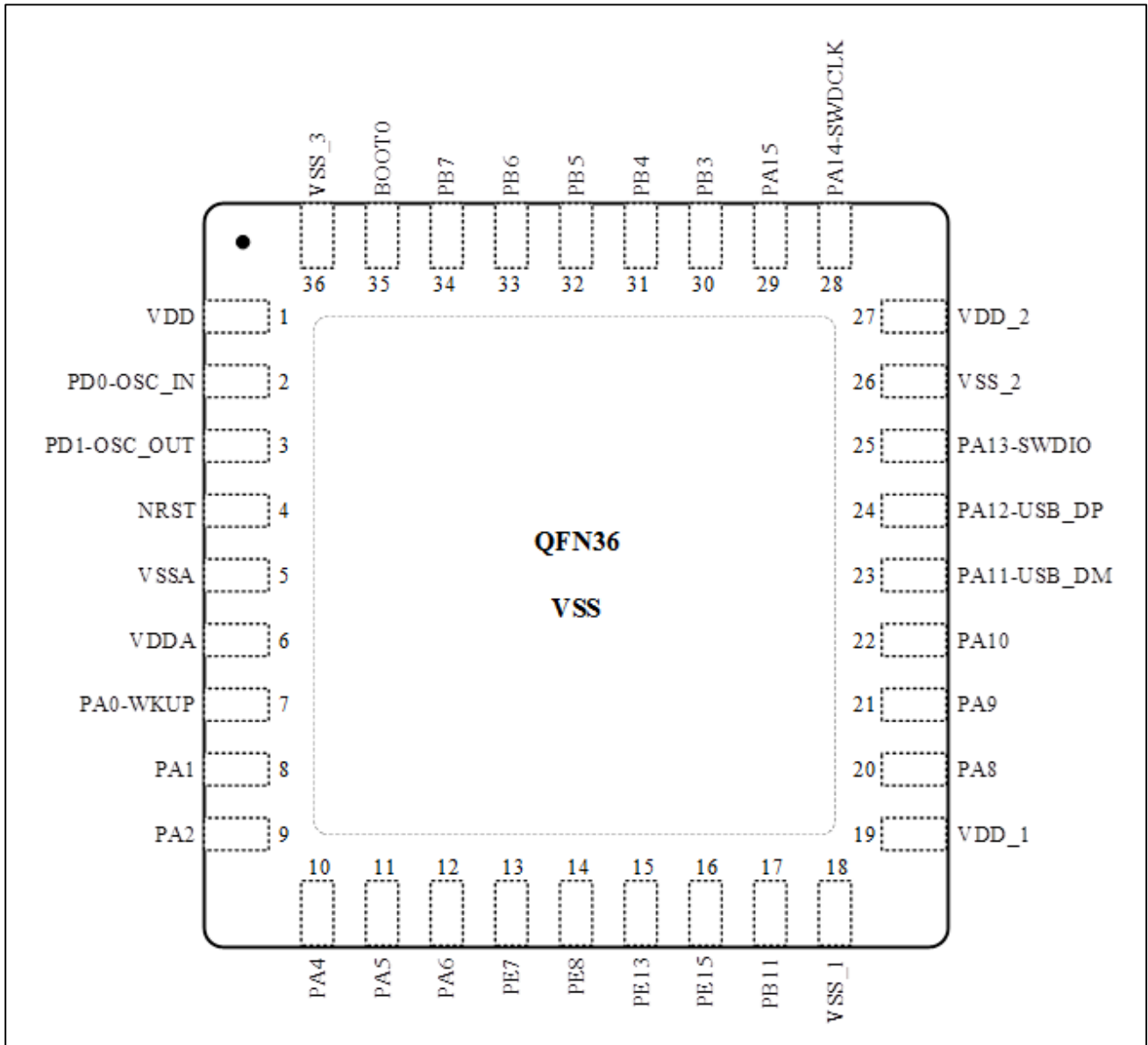
2 Product Model Resource configuration

Part number		N32G455TB	N32G455CB/C/E			N32G455RB/C/E			N32G455RG	N32G455MB/C/E			N32G455VB/C/E/G			
Flash (KB)		128	128	256	512	128	256	512	512	128	256	512	128	256	512	512
Data Flash (KB)		No	No	No	No	No	No	No	512	No	No	No	No	No	No	512
SRAM (KB)		80	80	144	144	80	144	144	144	80	144	144	80	144	144	144
CPU frequency		ARM Cortex-M4 @144MHz,180DMIPS														
Operating Voltage		1.8~3.6V/-40~105°C														
Timer	General	4														
	Advanced	2														
	Basic	2														
Communication interface	SPI	1	3 ⁽¹⁾													
	I2S	1	2													
	QSPI	Only Single Wire			1											
	I2C	2	3			4										
	USART	2	3													
	UART	1	3	4	4											
	USB	1		No	1											
	CAN	2														
	SDIO	No			1											
GPIO		26	37	42	51			65			80					
DMA Number of Channels		2 16Channel														
12bit ADC Number of channels		4 11Channel	4 16Channel			4 22Channel			4 33Channel			4 38Channel				
12bit DAC Number of channels		2 2Channel														
OPA/COMP		4/7	4/5	4/7	4/7			4/7			4/7					
Algorithm support		DES/3DES、AES、SHA1/SHA224/SHA256、SM1、SM3、SM4、SM7、MD5、CRC16/CRC32、TRNG														
Security protection		Read-write protection (RDP/WRP), Storage encryption, Partition protection, Secure startup														
OPA/COMP		QFN36	LQFP48	QFN48	LQFP64/QFN64			LQFP64	LQFP80			LQFP100				

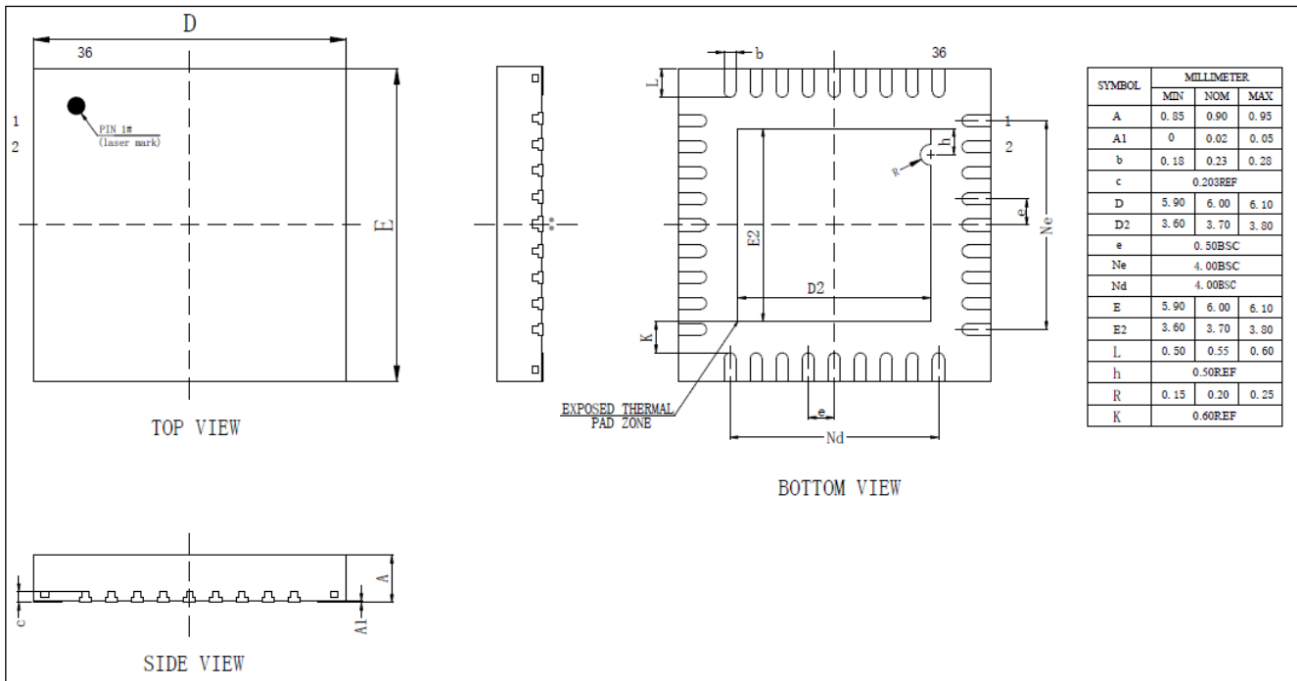
3 Package

3.1 QFN36 package

3.1.1 QFN36 pin distribution

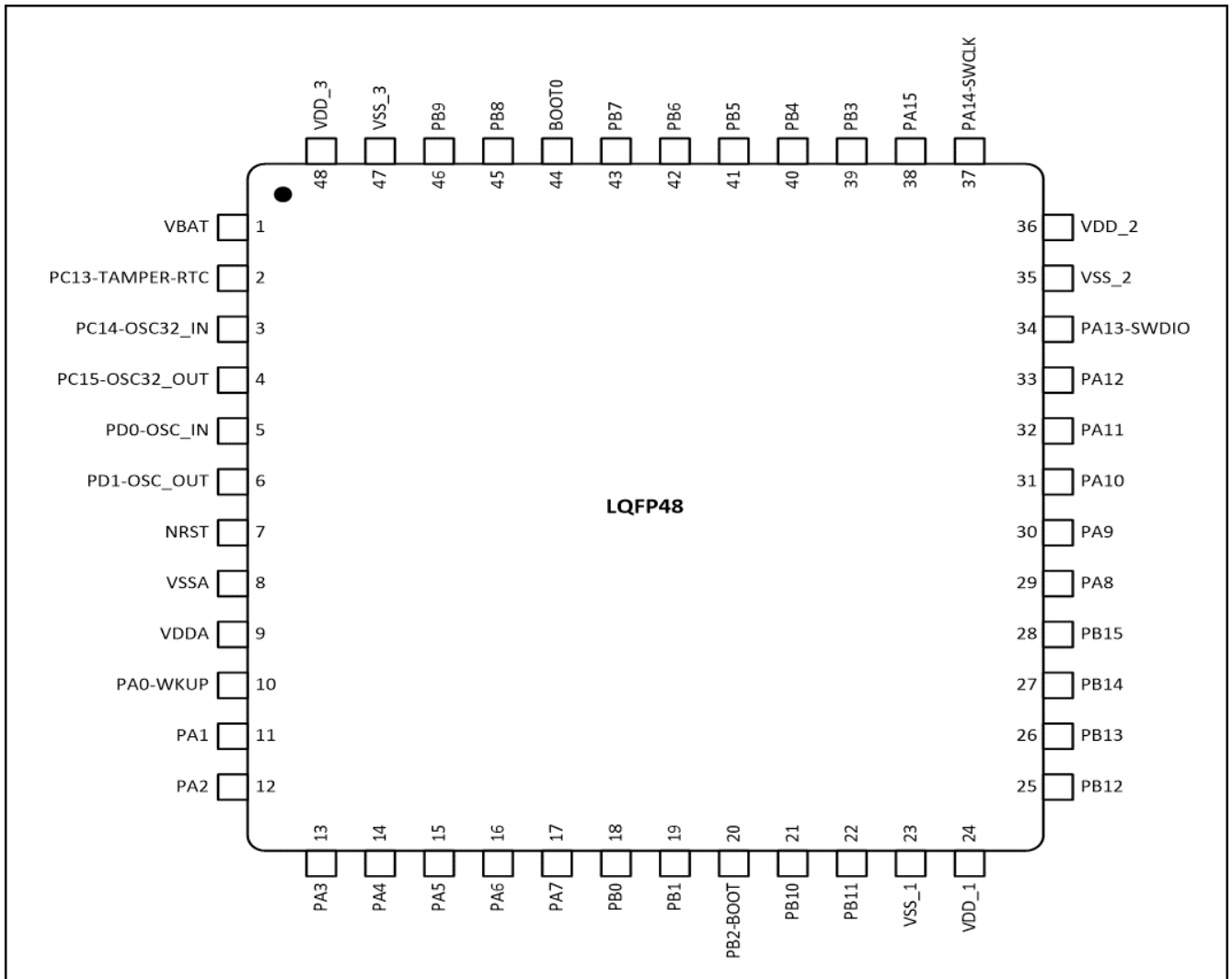


3.1.2 QFN36 package size

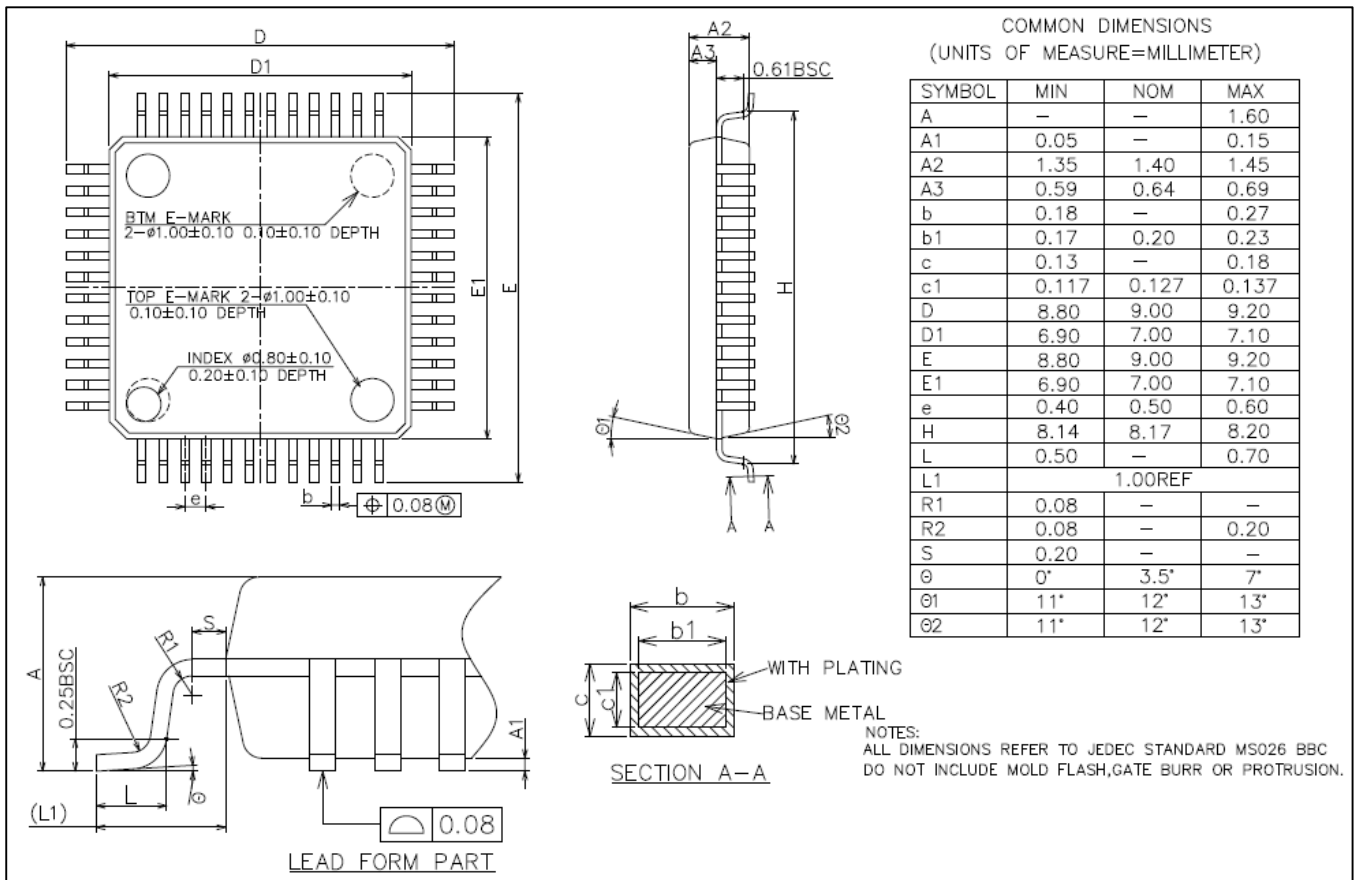


3.2 LQFP48 package

3.2.1 LQFP48 pin distribution

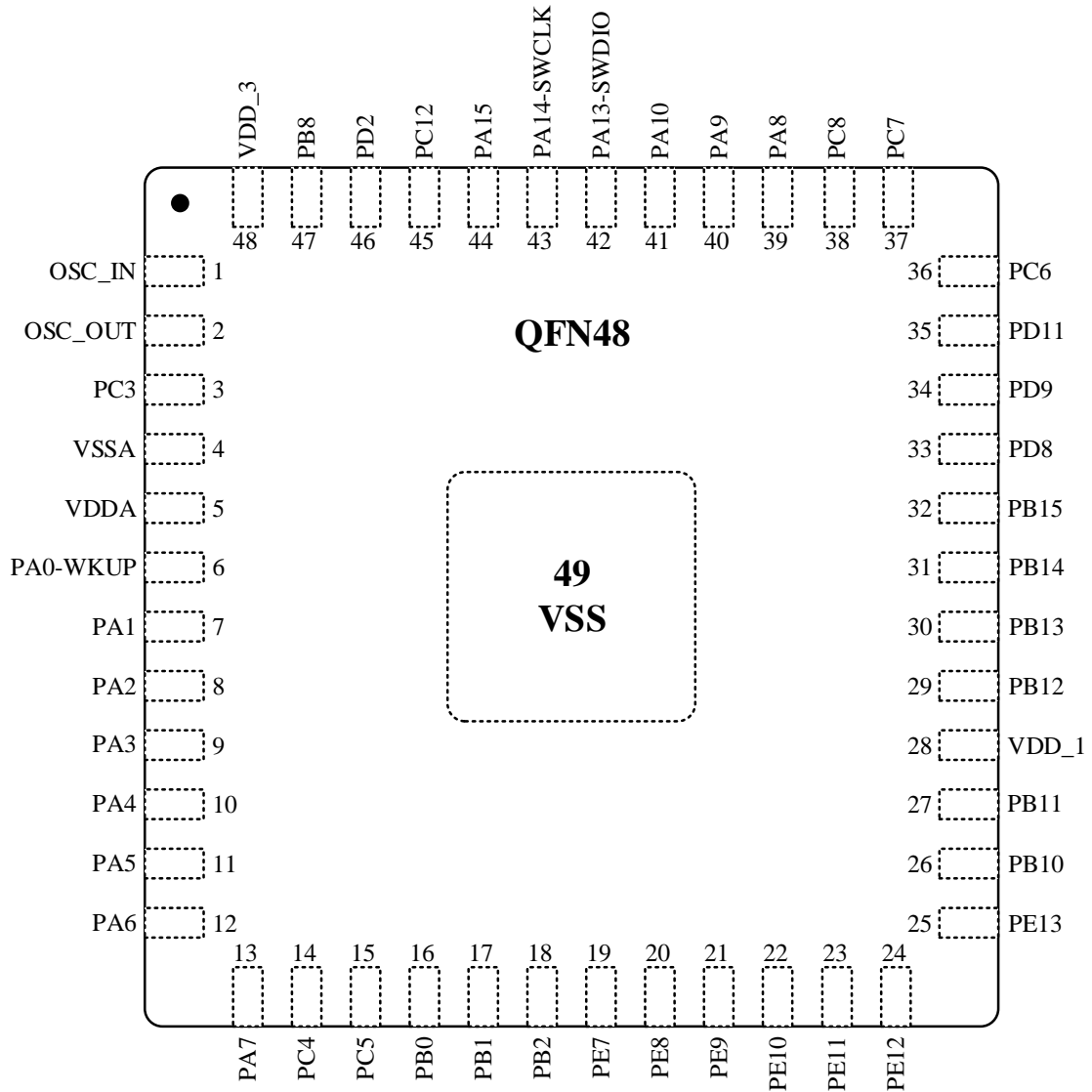


3.2.2 LQFP48 package size

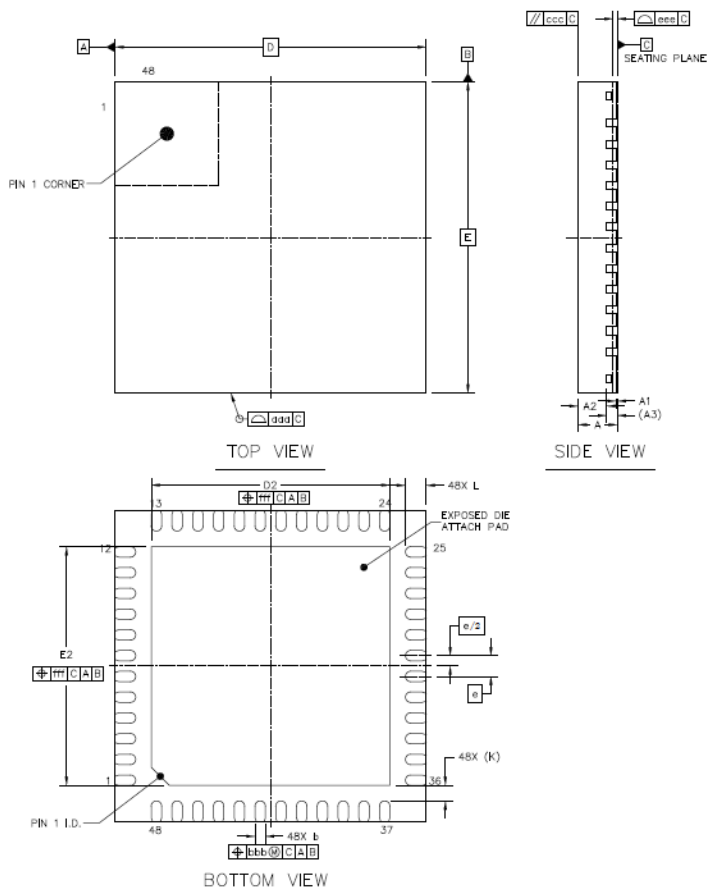


3.3 QFN48 package

3.3.1 QFN48 pin distribution



3.3.2 QFN48 package size



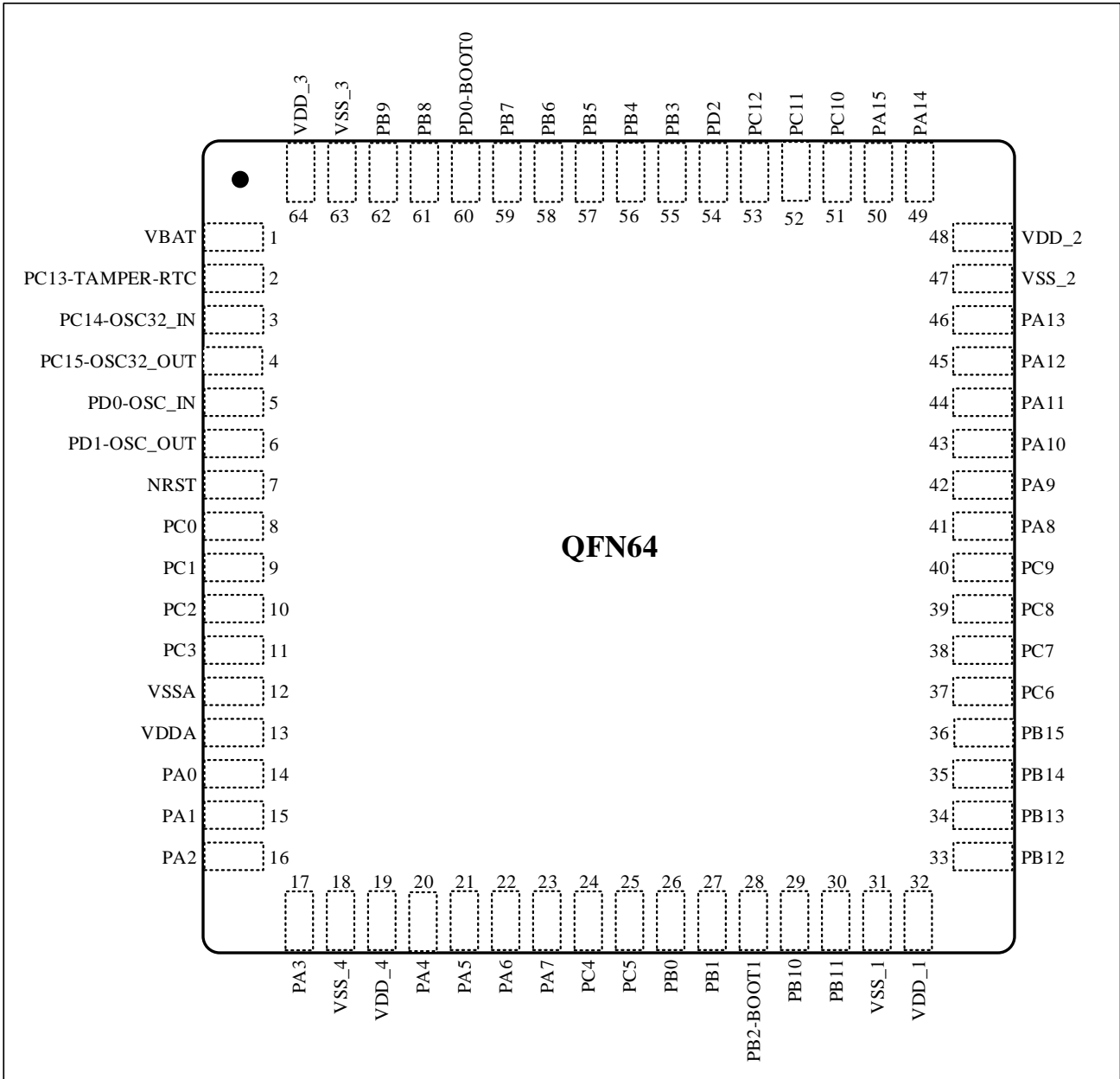
	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	0.7	0.75	0.8
STAND OFF	A1	0	0.02	0.05
MOLD THICKNESS	A2	----	0.55	----
L/F THICKNESS	A3		0.203 REF	
LEAD WIDTH	b	0.15	0.2	0.25
BODY SIZE	X	6 BSC		
	Y	6 BSC		
LEAD PITCH	e	0.4 BSC		
EP SIZE	X	D2	4.5	4.6
	Y	E2	4.5	4.6
LEAD LENGTH	L	0.3	0.4	0.5
LEAD TIP TO EXPOSED PAD EDGE	K	0.3 REF		
PACKAGE EDGE TOLERANCE	aaa	0.1		
MOLD FLATNESS	ccc	0.1		
COPLANARITY	eee	0.08		
LEAD OFFSET	bbb	0.07		
EXPOSED PAD OFFSET	fff	0.1		

NOTES

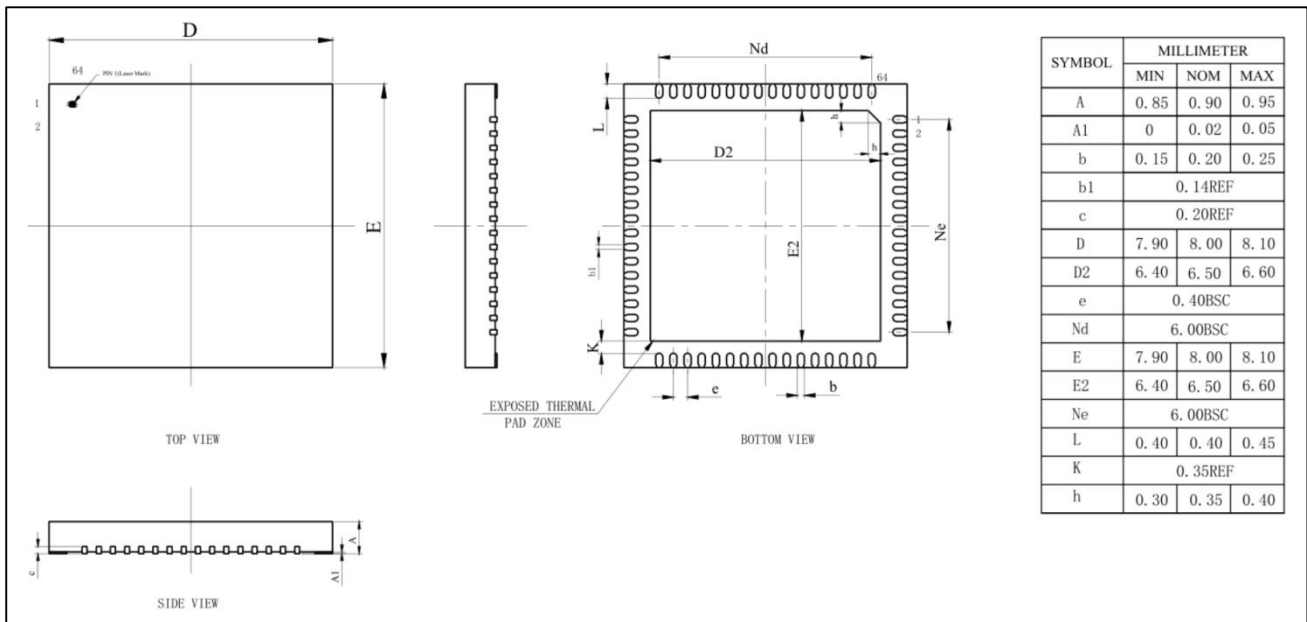
1. REFER TO JEDEC MO-220;
2. COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD;
3. BAN TO USE THE LEVEL 1 ENVIRONMENT-RELATED SUBSTANCES;
4. FINISH: Cu/EP • Sn8~20s

3.4 QFN64 package

3.4.1 QFN64 pin distribution

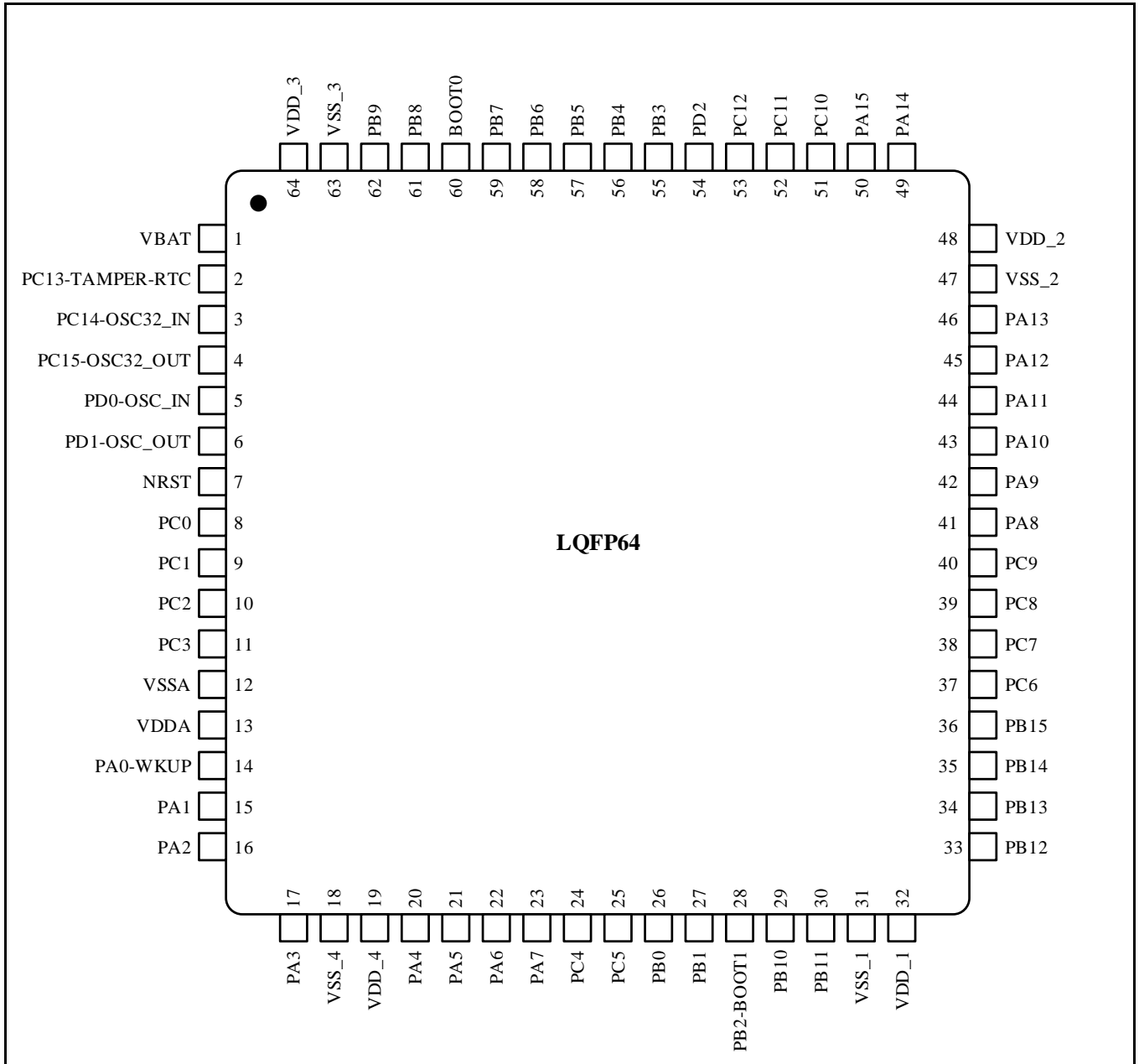


3.4.2 QFN64 package size

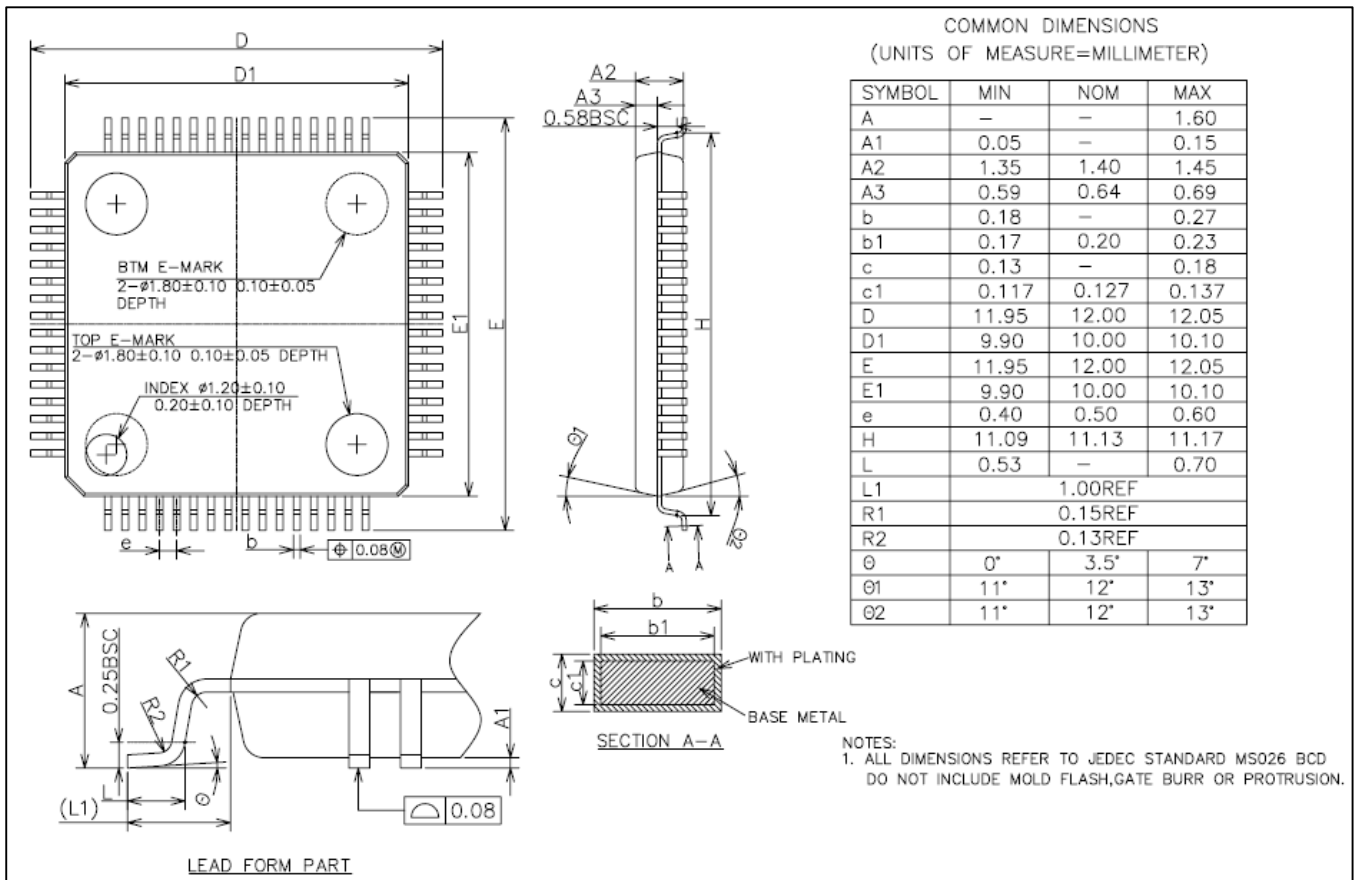


3.5 LQFP64 package

3.5.1 LQFP64 pin distribution

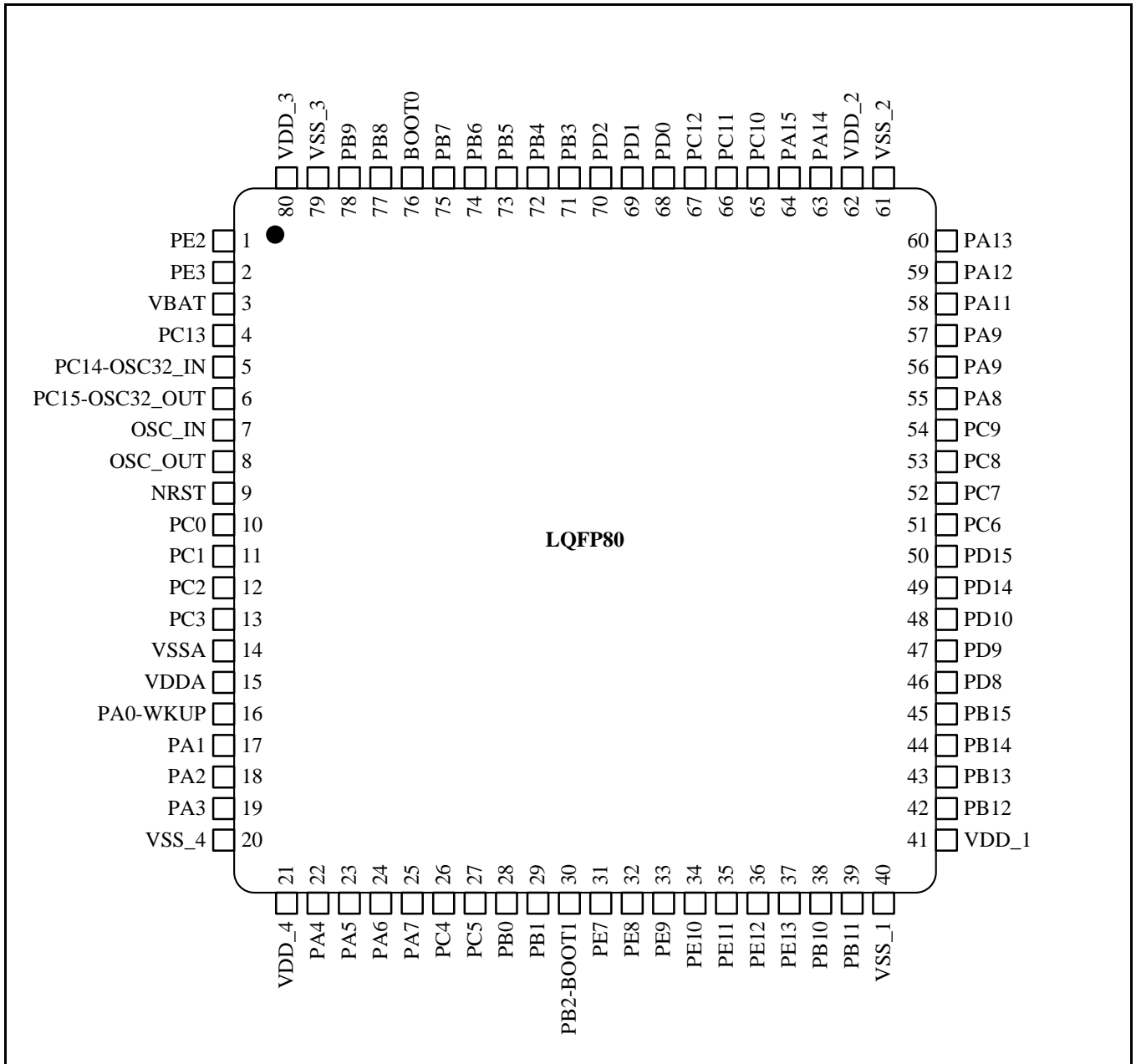


3.5.2 LQFP64 package size

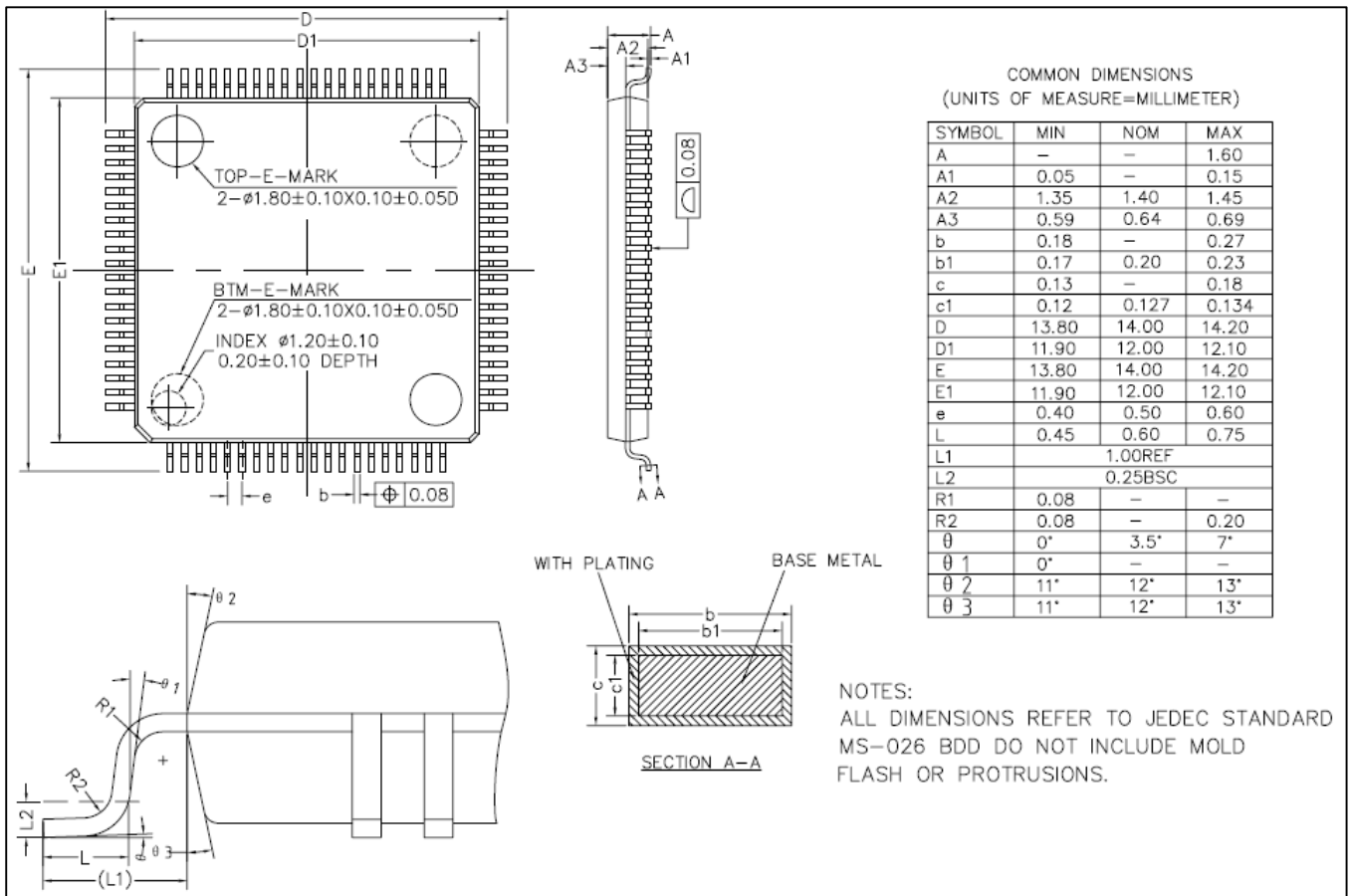


3.6 LQFP80 package

3.6.1 LQFP80 pin distribution

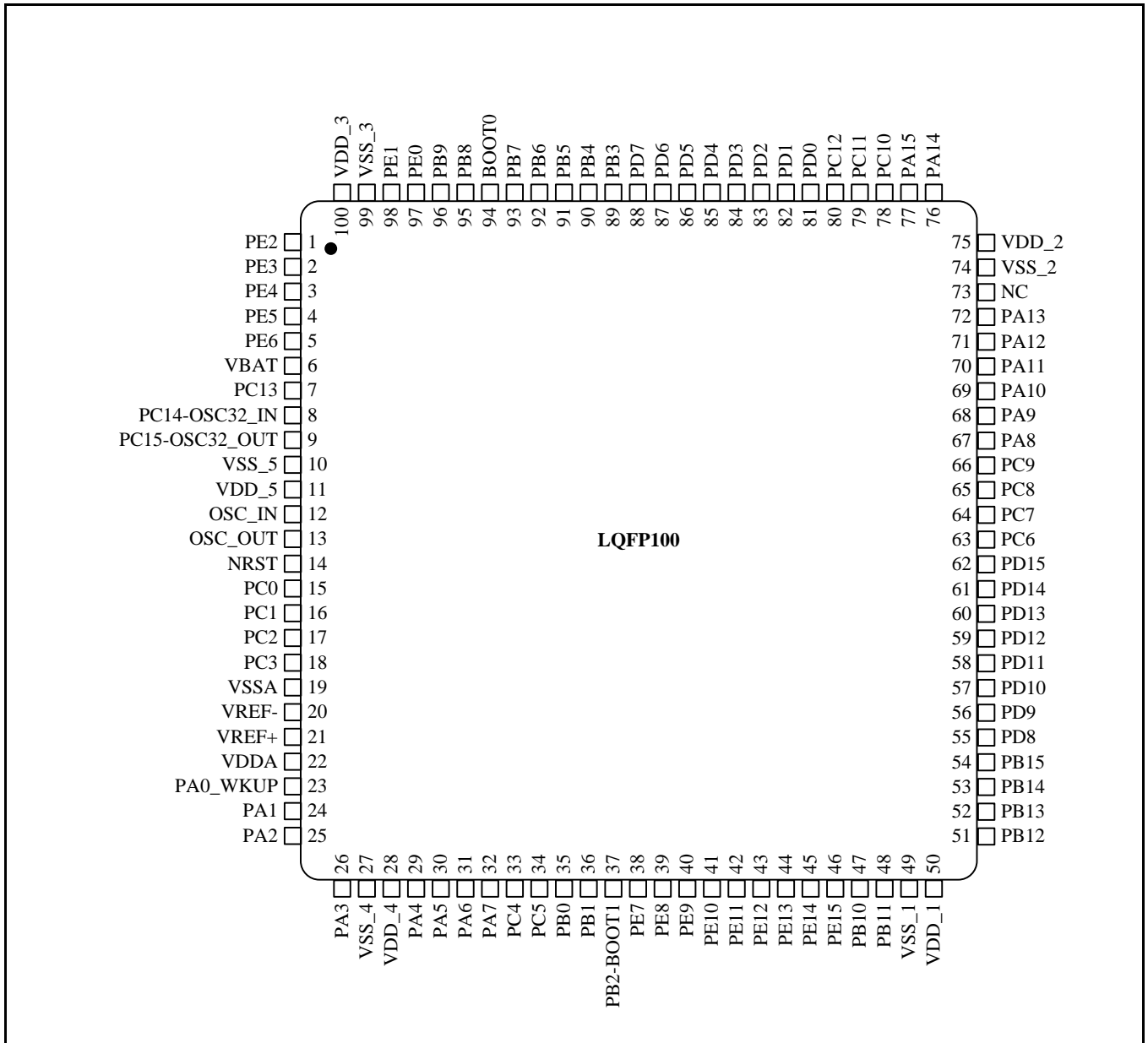


3.6.2 LQFP80 package size

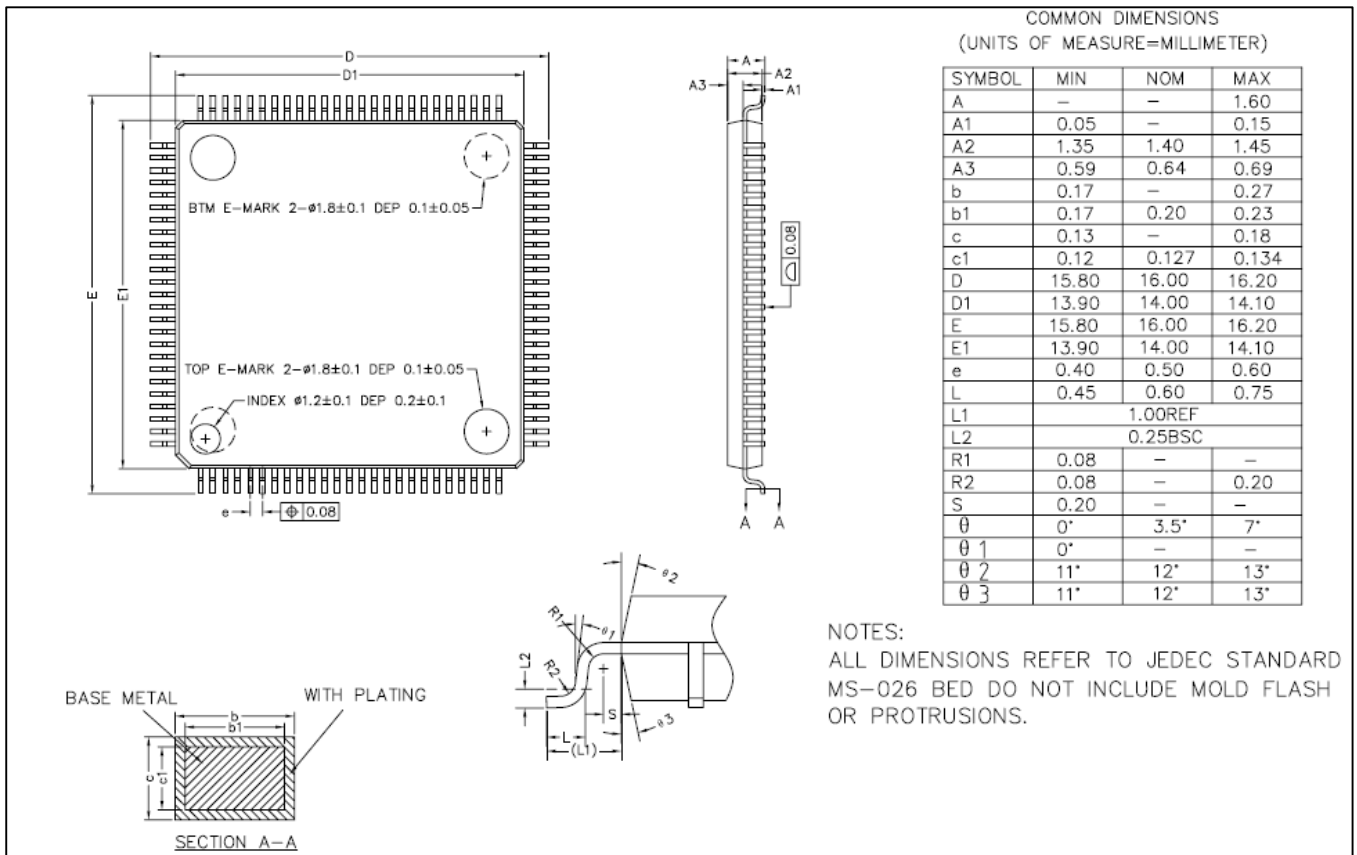


3.7 LQFP100 package

3.7.1 LQFP100 pin distribution



3.7.2 LQFP100 package size



4 Version history

Version	The date	Note
V1.0	2020.02.12	New document
V1.0.1	2020.11.10	1. Modify 3.2.1 pinout diagram 2. Added QFN48 package 3. Added N32G455CEQ7 model
V1.1	2022.04.26	1. Updated QFN48 package size 2. Delete SDIO eMMC format 3. Modified reset description in Key features
V1.2.0	2024.11.19	1. Add QFN36 package 2. Add QFN64 package 3. Modify Naming rules to Ordering information, modify ordering information table
V1.3.0	2025.08.21	1. Add N32G455VGL7 and N32G455RGL7
V1.3.0	2026.03.17	1. Modify the description in the main features section to “single-cycle hardware multiply instruction” 2. Modify the pin distribution of QFN64

5 Notice

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